



## Product/Process Change Notice - PCN 15\_0121 Rev. -

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This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

**PCN Title:** ADuM2200W/ADuM2201W Die Revision and Data Sheet Changes  
**Publication Date:** 08-Oct-2015  
**Effectivity Date:** 06-Jan-2016 *(the earliest date that a customer could expect to receive changed material)*

### Revision Description:

Initial Release

### Description Of Change

#### Die Changes:

1. Increased pulse width of edge pulses and refresh pulses.
2. Increased separation between consecutive pulses on rising edge and refresh high pulses.
3. Additional layer of polyimide passivation on top of the non-coil die.

#### Data Sheet Changes:

1. Increased Idd-Dynamic current specifications. See data sheet specification comparison attachment for resulting values.
2. Changed Voh/Vol test conditions from  $I_{ox} = -4mA/4mA$  to  $I_{ox} = -3.2mA/3.2mA$ .

### Reason For Change

#### Die Changes:

1. Ensure receiver can reliably detect all edge pulses and all refresh pulses.
2. Ensure 2nd pulse on rising edge or refresh high is consistently detected by receiver.
3. Polyimide offers the following advantages: improved ESD robustness, enhanced protection against die scratches, package stresses, surface ESD/EOS events and radiation.

#### Data Sheet Changes:

1. Increase in size of existing capacitors in receiver block caused increase in Idd-Dynamic current.
2. Express Voh/Vol levels with a load equal to the current required to drive two standard TTL gates.

### Impact of the change (positive or negative) on fit, form, function & reliability

No change to fit, form, or reliability. Improved functional robustness.

### Summary of Supporting Information

Qualification has been performed per AEC-Q100, Stress Test Qualification for Integrated Circuits. See attached Qualification Results Summary.

### Supporting Documents

**Attachment 1: Type:** Qualification Results Summary

ADI\_PCN\_15\_0121\_Rev\_-\_ADuM220xW\_SOIC\_W\_Qual\_Results\_Summary.pdf

**Attachment 2: Type:** Datasheet Specification Comparison

**Attachment 3: Type:** Datasheet Specification Comparison

ADI\_PCN\_15\_0121\_Rev\_-\_ADUM2201\_R2 IDD Data Sheet Comparison.pdf

**For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.**

**Americas:** [PCN\\_Americas@analog.com](mailto:PCN_Americas@analog.com)

**Europe:** [PCN\\_Europe@analog.com](mailto:PCN_Europe@analog.com)

**Japan:** [PCN\\_Japan@analog.com](mailto:PCN_Japan@analog.com)

**Rest of Asia:** [PCN\\_ROA@analog.com](mailto:PCN_ROA@analog.com)

**Appendix A - Affected ADI Models**

**Added Parts On This Revision - Product Family / Model Number (8)**

ADUM2200 / ADUM2200WARWZ	ADUM2200 / ADUM2200WARWZ-RL	ADUM2200 / ADUM2200WBRWZ	ADUM2200 / ADUM2200WBRWZ-RL	ADUM2201 / ADUM2201WARWZ
ADUM2201 / ADUM2201WARWZ-RL	ADUM2201 / ADUM2201WBRWZ	ADUM2201 / ADUM2201WBRWZ-RL		

**Appendix B - Revision History**

<b>Rev</b>	<b>Publish Date</b>	<b>Effectivity Date</b>	<b>Rev Description</b>
Rev. -	08-Oct-2015	06-Jan-2016	Initial Release

Analog Devices, Inc.

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